Microchip Technology - DSPIC33EP16GS202-I/SS Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	21
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 12x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep16gs202-i-ss

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2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT DIGITAL SIGNAL CONTROLLERS

Note 1: This data sheet summarizes the features of the dsPIC33EPXXGS202 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the dsPIC33EPXXGS202 family requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names which must always be connected:

- All VDD and VSS pins
  (see **Section 2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins
  regardless if ADC module is not used (see **Section 2.2 "Decoupling Capacitors"**)
- VCAP
  (see **Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)"**)
- $\overline{\text{MCLR}}$ pin
  (see **Section 2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins
  used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **Section 2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins
  when external oscillator source is used (see **Section 2.6 "External Oscillator Pins"**)

2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** Recommendation of 0.1 µF (100 nF), 10-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended to use ceramic capacitors.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise, above tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB track inductance.

4.3 Data Address Space

The dsPIC33EPXXGS202 family CPU has a separate 16-bit wide data memory space. The Data Space is accessed using separate Address Generation Units (AGUs) for read and write operations. The data memory map is shown in Figure 4-4.

All Effective Addresses (EAs) in the data memory space are 16 bits wide and point to bytes within the Data Space. This arrangement gives a base Data Space address range of 64 Kbytes or 32K words.

The lower half of the data memory space (i.e., when EA<15> = 0) is used for implemented memory addresses, while the upper half (EA<15> = 1) is reserved for the Program Space Visibility (PSV).

dsPIC33EPXXGS202 family devices implement up to 12 Kbytes of data memory. If an EA points to a location outside of this area, an all-zero word or byte is returned.

4.3.1 DATA SPACE WIDTH

The data memory space is organized in byte-addressable, 16-bit wide blocks. Data is aligned in data memory and registers as 16-bit words, but all Data Space EAs resolve to bytes. The Least Significant Bytes (LSBs) of each word have even addresses, while the Most Significant Bytes (MSBs) have odd addresses.

4.3.2 DATA MEMORY ORGANIZATION AND ALIGNMENT

To maintain backward compatibility with PIC® MCU devices and improve Data Space memory usage efficiency, the dsPIC33EPXXGS202 family instruction set supports both word and byte operations. As a consequence of byte accessibility, all Effective Address calculations are internally scaled to step through word-aligned memory. For example, the core recognizes that Post-Modified Register Indirect Addressing mode [Ws++] results in a value of Ws + 1 for byte operations and Ws + 2 for word operations.

A data byte read, reads the complete word that contains the byte, using the LSb of any EA to determine which byte to select. The selected byte is placed onto the LSB of the data path. That is, data memory and registers are organized as two parallel, byte-wide entities with shared (word) address decode, but separate write lines. Data byte writes only write to the corresponding side of the array or register that matches the byte address.

All word accesses must be aligned to an even address. Misaligned word data fetches are not supported, so care must be taken when mixing byte and word operations, or translating from 8-bit MCU code. If a misaligned read or write is attempted, an address error trap is generated. If the error occurred on a read, the instruction underway is completed. If the error occurred on a write, the instruction is executed but the write does not occur. In either case, a trap is then executed, allowing the system and/or user application to examine the machine state prior to execution of the address Fault.

All byte loads into any W register are loaded into the LSB; the MSB is not modified.

A Sign-Extend (SE) instruction is provided to allow user applications to translate 8-bit signed data to 16-bit signed values. Alternatively, for 16-bit unsigned data, user applications can clear the MSB of any W register by executing a Zero-Extend (ZE) instruction on the appropriate address.

4.3.3 SFR SPACE

The first 4 Kbytes of the Near Data Space, from 0x0000 to 0x0FFF, are primarily occupied by Special Function Registers (SFRs). These are used by the dsPIC33EPXXGS202 family core and peripheral modules for controlling the operation of the device.

SFRs are distributed among the modules that they control, and are generally grouped together by module. Much of the SFR space contains unused addresses; these are read as '0'.

Note:	The actual set of peripheral features and interrupts varies by the device. Refer to the corresponding device tables and pinout diagrams for device-specific information.

4.3.4 NEAR DATA SPACE

The 8-Kbyte area, between 0x0000 and 0x1FFF, is referred to as the Near Data Space. Locations in this space are directly addressable through a 13-bit absolute address field within all memory direct instructions. Additionally, the whole Data Space is addressable using MOV instructions, which support Memory Direct Addressing mode with a 16-bit address field, or by using Indirect Addressing mode using a Working register as an Address Pointer.

FIGURE 4-6: PAGED DATA MEMORY SPACE

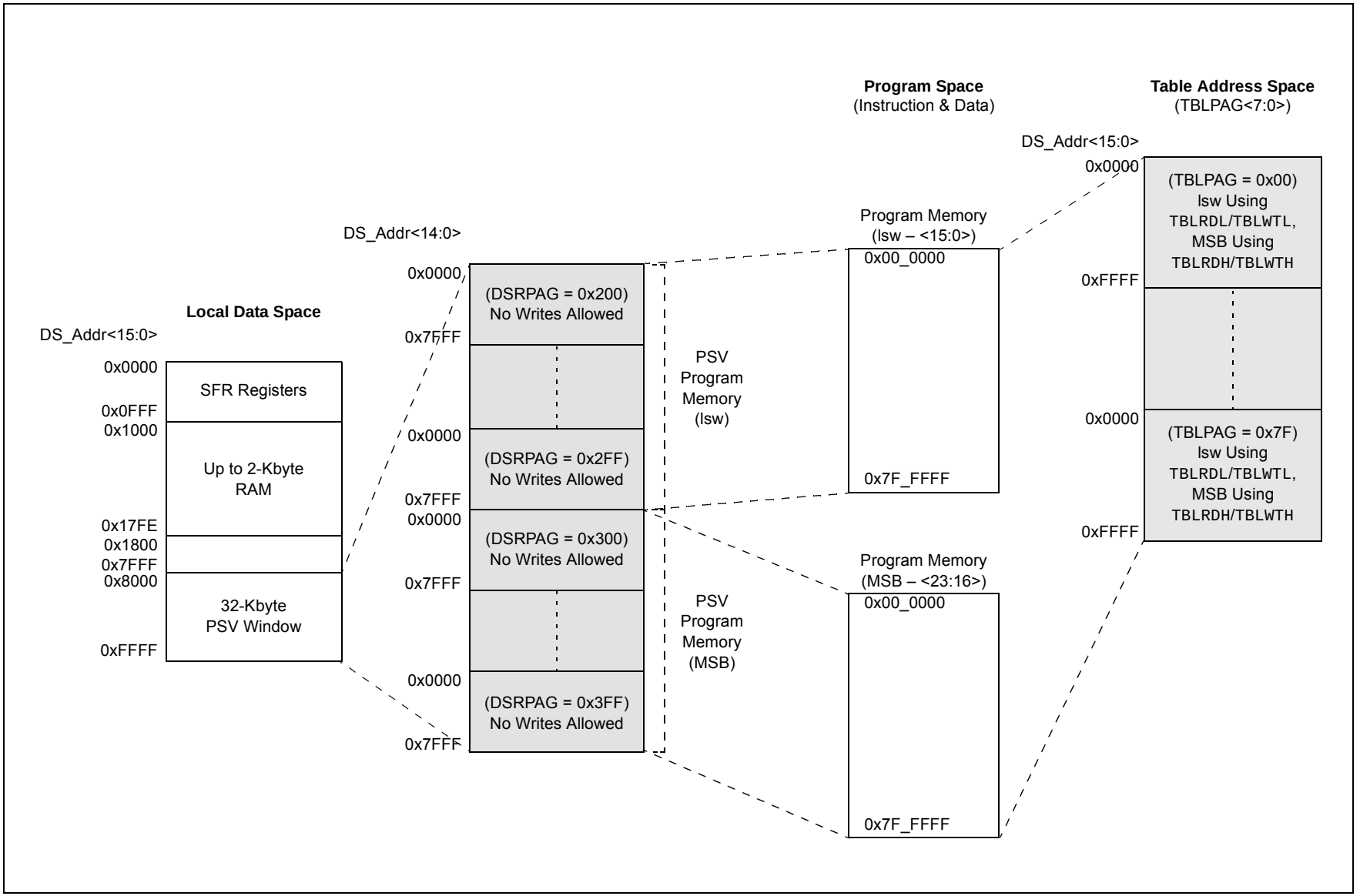


FIGURE 4-9: BIT-REVERSED ADDRESSING EXAMPLE

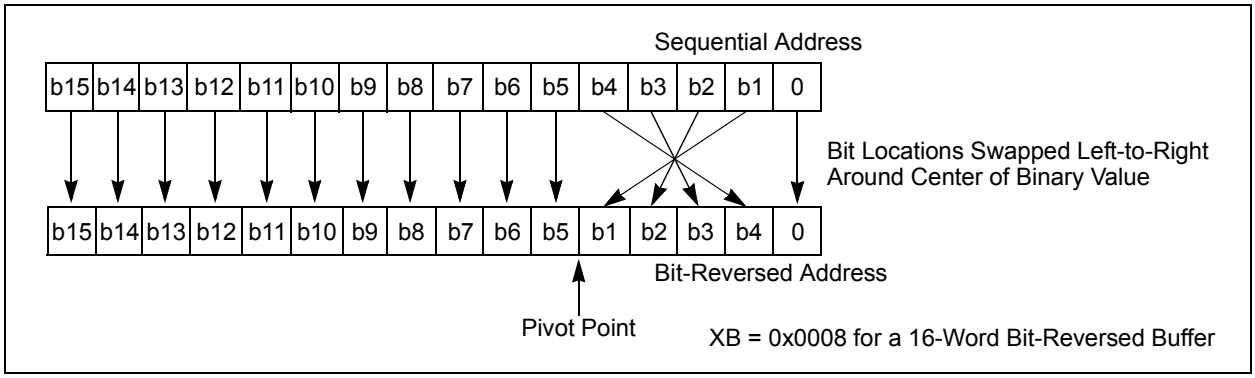


TABLE 4-26: BIT-REVERSED ADDRESSING SEQUENCE (16-ENTRY)

Normal Address					Bit-Reversed Address				
A3	**A2**	**A1**	**A0**	**Decimal**	**A3**	**A2**	**A1**	**A0**	**Decimal**
0	0	0	0	0	0	0	0	0	0
0	0	0	1	1	1	0	0	0	8
0	0	1	0	2	0	1	0	0	4
0	0	1	1	3	1	1	0	0	12
0	1	0	0	4	0	0	1	0	2
0	1	0	1	5	1	0	1	0	10
0	1	1	0	6	0	1	1	0	6
0	1	1	1	7	1	1	1	0	14
1	0	0	0	8	0	0	0	1	1
1	0	0	1	9	1	0	0	1	9
1	0	1	0	10	0	1	0	1	5
1	0	1	1	11	1	1	0	1	13
1	1	0	0	12	0	0	1	1	3
1	1	0	1	13	1	0	1	1	11
1	1	1	0	14	0	1	1	1	7
1	1	1	1	15	1	1	1	1	15

NOTES:

TABLE 7-1: INTERRUPT VECTOR DETAILS (CONTINUED)

Interrupt Source	Vector #	IRQ #	IVT Address	Interrupt Bit Location		
				Flag	Enable	Priority
Reserved	126-158	118-150	0x000100-0x000140	—	—	—
AN8 Conversion Done	159	151	0x000142	IFS9<7>	IEC9<7>	IPC37<14:12>
AN9 Conversion Done	160	152	0x000144	IFS9<8>	IEC9<8>	IPC38<2:0>
AN10 Conversion Done	161	153	0x000146	IFS9<9>	IEC9<9>	IPC38<6:4>
AN11 Conversion Done	162	154	0x000148	IFS9<10>	IEC9<10>	IPC38<10:8>
Reserved	163-164	155-156	0x00014A-0x00014C	—	—	—
AN14 Conversion Done	165	157	0x00014E	IFS9<13>	IEC9<13>	IPC39<6:4>
Reserved	163-180	155-172	0x00014A-0x00016C	—	—	—
I2C1 – I2C1 Bus Collision	181	173	0x00016E	IFS10<13>	IEC10<13>	IPC43<6:4>
Reserved	182-184	174-176	0x000170-0x000174	—	—	—
ADCMP0 – ADC Digital Comparator 0	185	177	0x000176	IFS11<1>	IEC11<1>	IPC44<6:4>
ADCMP1 – ADC Digital Comparator 1	186	178	0x000178	IFS11<2>	IEC11<2>	IPC44<10:8>
ADFL0 – ADC Filter 0	187	179	0x00017A	IFS11<3>	IEC11<3>	IPC44<14:12>
Reserved	188-253	180-245	0x00017C-0x0001FE	—	—	—

7.3 Interrupt Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page contains the latest updates and additional information.

7.3.1 KEY RESOURCES

- **"Interrupts"** (DS70000600) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

7.4 Interrupt Control and Status Registers

dsPIC33EPXXGS202 family devices implement the following registers for the interrupt controller:

- INTCON1
- INTCON2
- INTCON3
- INTCON4
- INTTREG

7.4.1 INTCON1 THROUGH INTCON4

Global interrupt control functions are controlled from INTCON1, INTCON2, INTCON3 and INTCON4.

INTCON1 contains the Interrupt Nesting Disable bit (NSTDIS), as well as the control and status flags for the processor trap sources.

The INTCON2 register controls external interrupt request signal behavior, contains the Global Interrupt Enable bit (GIE) and the Alternate Interrupt Vector Table Enable bit (AIVTEN).

INTCON3 contains the status flags for the Auxiliary PLL and DO stack overflow status trap sources.

The INTCON4 register contains the Software Generated Hard Trap Status bit (SGHT).

7.4.2 IFSx

The IFSx registers maintain all of the interrupt request flags. Each source of interrupt has a status bit, which is set by the respective peripherals or external signal and is cleared via software.

7.4.3 IECx

The IECx registers maintain all of the interrupt enable bits. These control bits are used to individually enable interrupts from the peripherals or external signals.

7.4.4 IPCx

The IPCx registers are used to set the Interrupt Priority Level (IPL) for each source of interrupt. Each user interrupt sources can be assigned to one of seven priority levels.

7.4.5 INTTREG

The INTTREG register contains the associated interrupt vector number and the new CPU Interrupt Priority Level, which are latched into the Vector Number (VECNUM<7:0>) and Interrupt Level bits (ILR<3:0>) fields in the INTTREG register. The new Interrupt Priority Level is the priority of the pending interrupt.

The interrupt sources are assigned to the IFSx, IECx and IPCx registers in the same sequence as they are listed in Table 7-1. For example, the INT0 (External Interrupt 0) is shown as having Vector Number 8 and a natural order priority of 0. Thus, the INT0IF bit is found in IFS0<0>, the INT0IE bit in IEC0<0> and the INT0IP<2:0> bits in the first position of IPC0 (IPC0<2:0>).

7.4.6 STATUS/CONTROL REGISTERS

Although these registers are not specifically part of the interrupt control hardware, two of the CPU Control registers contain bits that control interrupt functionality. For more information on these registers refer to **"CPU"** (DS70359) in the *"dsPIC33/PIC24 Family Reference Manual"*.

- The CPU STATUS Register, SR, contains the IPL<2:0> bits (SR<7:5>). These bits indicate the current CPU Interrupt Priority Level. The user software can change the current CPU Interrupt Priority Level by writing to the IPLx bits.
- The CORCON register contains the IPL3 bit which, together with IPL<2:0>, also indicates the current CPU priority level. IPL3 is a read-only bit so that trap events cannot be masked by the user software.

All Interrupt registers are described in Register 7-3 through Register 7-7 in the following pages.

9.0 POWER-SAVING FEATURES

Note 1: This data sheet summarizes the features of the dsPIC33EPXXGS202 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Watchdog Timer and Power-Saving Modes"** (DS70615) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com)

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXGS202 family devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of peripherals being clocked constitutes lower consumed power.

dsPIC33EPXXGS202 family devices can manage power consumption in four ways:

- Clock Frequency
- Instruction-Based Sleep and Idle modes
- Software-Controlled Doze mode
- Selective Peripheral Control in Software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

9.1 Clock Frequency and Clock Switching

The dsPIC33EPXXGS202 family devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSCx bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 8.0 "Oscillator Configuration"**.

9.2 Instruction-Based Power-Saving Modes

The dsPIC33EPXXGS202 family devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembler syntax of the PWRSAV instruction is shown in Example 9-1.

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

EXAMPLE 9-1: PWRSAV INSTRUCTION SYNTAX

```
PWRSAV  #SLEEP_MODE    ; Put the device into Sleep mode
PWRSAV  #IDLE_MODE     ; Put the device into Idle mode
```

REGISTER 9-1: PMD1: PERIPHERAL MODULE DISABLE CONTROL REGISTER 1

U-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	U-0
—	—	T3MD	T2MD	T1MD	—	PWMMD	—
bit 15							bit 8

R/W-0	U-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0
I2C1MD	—	U1MD	—	SPI1MD	—	—	ADCMD
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **T3MD:** Timer3 Module Disable bit
1 = Timer3 module is disabled
0 = Timer3 module is enabled

bit 12 **T2MD:** Timer2 Module Disable bit
1 = Timer2 module is disabled
0 = Timer2 module is enabled

bit 11 **T1MD:** Timer1 Module Disable bit
1 = Timer1 module is disabled
0 = Timer1 module is enabled

bit 10 **Unimplemented:** Read as '0'

bit 9 **PWMMD:** PWM Module Disable bit
1 = PWM module is disabled
0 = PWM module is enabled

bit 8 **Unimplemented:** Read as '0'

bit 7 **I2C1MD:** I2C1 Module Disable bit
1 = I2C1 module is disabled
0 = I2C1 module is enabled

bit 6 **Unimplemented:** Read as '0'

bit 5 **U1MD:** UART1 Module Disable bit
1 = UART1 module is disabled
0 = UART1 module is enabled

bit 4 **Unimplemented:** Read as '0'

bit 3 **SPI1MD:** SPI1 Module Disable bit
1 = SPI1 module is disabled
0 = SPI1 module is enabled

bit 2-1 **Unimplemented:** Read as '0'

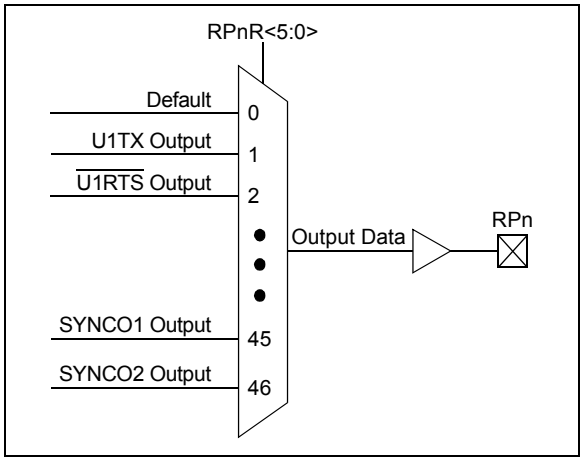
bit 0 **ADCMD:** ADC Module Disable bit
1 = ADC module is disabled
0 = ADC module is enabled

10.4.5 OUTPUT MAPPING

In contrast to inputs, the outputs of the Peripheral Pin Select options are mapped on the basis of the pin. In this case, a control register associated with a particular pin dictates the peripheral output to be mapped. The RPORx registers are used to control output mapping. Each register contains sets of 6-bit fields, with each set associated with one RPn pin (see Register 10-16 through Register 10-26). The value of the bit field corresponds to one of the peripherals and that peripheral's output is mapped to the pin (see Table 10-2 and Figure 10-3).

A null output is associated with the Output register Reset value of '0'. This is done to ensure that remappable outputs remain disconnected from all output pins by default.

FIGURE 10-3: MULTIPLEXING REMAPPABLE OUTPUTS FOR RPn



10.4.5.1 Mapping Limitations

The control schema of the peripheral select pins is not limited to a small range of fixed peripheral configurations. There are no mutual or hardware-enforced lockouts between any of the peripheral mapping SFRs. Literally any combination of peripheral mappings across any or all of the RPn pins is possible. This includes both many-to-one and one-to-many mappings of peripheral inputs, and outputs to pins. While such mappings may be technically possible from a configuration point of view, they may not be supportable from an electrical point of view.

TABLE 10-2: OUTPUT SELECTION FOR REMAPPABLE PINS (RPn)

Function	RPnR<5:0>	Output Name
Default PORT	000000	RPn tied to Default Pin
U1TX	000001	RPn tied to UART1 Transmit
$\overline{\text{U1RTS}}$/BCLK	000010	RPn tied to UART1 Request-to-Send
SDO1	000101	RPn tied to SPI1 Data Output
SCK1	000110	RPn tied to SPI1 Clock Output
$\overline{\text{SS1}}$	000111	RPn tied to SPI1 Slave Select
OC1	010000	RPn tied to Output Compare 1 Output
ACMP1	011000	RPn tied to Analog Comparator 1 Output
ACMP2	011001	RPn tied to Analog Comparator 2 Output
SYNCO1	101101	RPn tied to PWM Primary Master Time Base Sync Output
SYNCO2	101110	RPn tied to PWM Secondary Master Time Base Sync Output

NOTES:

NOTES:

REGISTER 19-20: ADTRIGxL: ADC CHANNEL TRIGGER x SELECTION REGISTER LOW (x = 0 to 3)

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	TRGSRC(4x+1)<4:0>				
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	TRGSRC(4x)<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **TRGSRC(4x+1)<4:0>:** Trigger Source Selection for Corresponding Analog Inputs bits

11111 = ADTRG31
11110 = Reserved
11101 = Reserved
11100 = Reserved
11011 = Reserved
11010 = PWM Generator 3 current-limit trigger
11001 = PWM Generator 2 current-limit trigger
11000 = PWM Generator 1 current-limit trigger
10111 = Reserved
10110 = Output Compare 1 trigger
10101 = Reserved
10100 = Reserved
10011 = Reserved
10010 = Reserved
10001 = PWM Generator 3 secondary trigger
10000 = PWM Generator 2 secondary trigger
01111 = PWM Generator 1 secondary trigger
01110 = PWM secondary Special Event Trigger
01101 = Timer2 period match
01100 = Timer1 period match
01011 = Reserved
01010 = Reserved
01001 = Reserved
01000 = Reserved
00111 = PWM Generator 3 primary trigger
00110 = PWM Generator 2 primary trigger
00101 = PWM Generator 1 primary trigger
00100 = PWM Special Event Trigger
00011 = Reserved
00010 = Level software trigger
00001 = Common software trigger
00000 = No trigger is enabled

bit 7-5 **Unimplemented:** Read as '0'

21.2 PGA Resources

Many useful resources are provided on the main product page of the Microchip website for the devices listed in this data sheet. This product page contains the latest updates and additional information.

21.2.1 KEY RESOURCES

- **"Programmable Gain Amplifier (PGA)"** (DS70005146) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 21-1: PGAxCON: PGAx CONTROL REGISTER (x = 1,2)

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PGAEN	—	SELPI2	SELPI1	SELPI0	SELNI2	SELNI1	SELNI0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	GAIN2	GAIN1	GAIN0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **PGAEN:** PGAx Enable bit
1 = PGAx module is enabled
0 = PGAx module is disabled (reduces power consumption)

bit 14 **Unimplemented:** Read as '0'

bit 13-11 **SELPI<2:0>:** PGAx Positive Input Selection bits
111 = Reserved
110 = Reserved
101 = Reserved
100 = Reserved
011 = Reserved
010 = PGAxP3
001 = PGAxP2
000 = PGAxP1

bit 10-8 **SELNI<2:0>:** PGAx Negative Input Selection bits
111 = Reserved
110 = Reserved
101 = Reserved
100 = Reserved
011 = Ground (Single-Ended mode)
010 = Reserved
001 = PGAxN2
000 = Ground (Single-Ended mode)

bit 7-3 **Unimplemented:** Read as '0'

25.1 DC Characteristics

TABLE 25-1: OPERATING MIPS vs. VOLTAGE

Characteristic	VDD Range (in Volts)	Temperature Range (in °C)	Maximum MIPS
			dsPIC33EPXXGS202 Family
—	3.0V to 3.6V(1)	-40°C to +85°C	70
—	3.0V to 3.6V(1)	-40°C to +125°C	60

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules (ADC, PGAs and comparators) may have degraded performance. Device functionality is tested but not characterized. Refer to Parameter BO10 in Table 25-13 for the minimum and maximum BOR values.

TABLE 25-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Typ.	Max.	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
Extended Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+140	°C
Operating Ambient Temperature Range	TA	-40	—	+125	°C
Power Dissipation: Internal Chip Power Dissipation: PINT = VDD x (IDD – Σ IOH) I/O Pin Power Dissipation: I/O = Σ ({VDD – VOH} x IOH) + Σ (VOL x IOL)	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/θJA			W

TABLE 25-3: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Typ.	Max.	Unit	Notes
Package Thermal Resistance, 28-Pin QFN-S	θJA	30.0	—	°C/W	1
Package Thermal Resistance, 28-Pin UQFN	θJA	26.0	—	°C/W	1
Package Thermal Resistance, 28-Pin SOIC	θJA	69.7	—	°C/W	1
Package Thermal Resistance, 28-Pin SSOP	θJA	71.0	—	°C/W	1

Note 1: Junction to ambient thermal resistance, Theta-JA (θJA) numbers are achieved by package simulations.

TABLE 25-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
	IIL	**Input Leakage Current(2,3)**					
DI50		I/O Pins 5V Tolerant(4)	-1	—	+1	µA	VSS ≤ VPIN ≤ VDD, pin at high-impedance
DI51		I/O Pins Not 5V Tolerant(4)	-1	—	+1	µA	VSS ≤ VPIN ≤ VDD, pin at high-impedance, -40°C ≤ TA ≤ +85°C
DI51a		I/O Pins Not 5V Tolerant(4)	-1	—	+1	µA	Analog pins shared with external reference pins, -40°C ≤ TA ≤ +85°C
DI51b		I/O Pins Not 5V Tolerant(4)	-1	—	+1	µA	VSS ≤ VPIN ≤ VDD, pin at high-impedance, -40°C ≤ TA ≤ +125°C
DI51c		I/O Pins Not 5V Tolerant(4)	-1	—	+1	µA	Analog pins shared with external reference pins, -40°C ≤ TA ≤ +125°C
DI55		$\overline{\text{MCLR}}$	-5	—	+5	µA	VSS ≤ VPIN ≤ VDD
DI56		OSC1	-5	—	+5	µA	VSS ≤ VPIN ≤ VDD, XT and HS modes

Note 1: Data in “Typ.” column is at 3.3V, +25°C unless otherwise stated.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: See the **“Pin Diagrams”** section for the 5V tolerant I/O pins.

5: VIL Source < (VSS – 0.3). Characterized but not tested.

6: VIH source > (VDD + 0.3) for non-5V tolerant pins only.

7: Digital 5V tolerant pins do not have an internal high side diode to VDD, and therefore, cannot tolerate any “positive” input injection current.

8: |Injection Currents| > 0 can affect the ADC results by approximately 4-6 counts.

9: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted, provided the mathematical “absolute instantaneous” sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

25.2 AC Characteristics and Timing Parameters

This section defines the dsPIC33EPXXGS202 family AC characteristics and timing parameters.

TABLE 25-15: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended Operating voltage VDD range as described in **Section 25.1 "DC Characteristics"**.

FIGURE 25-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

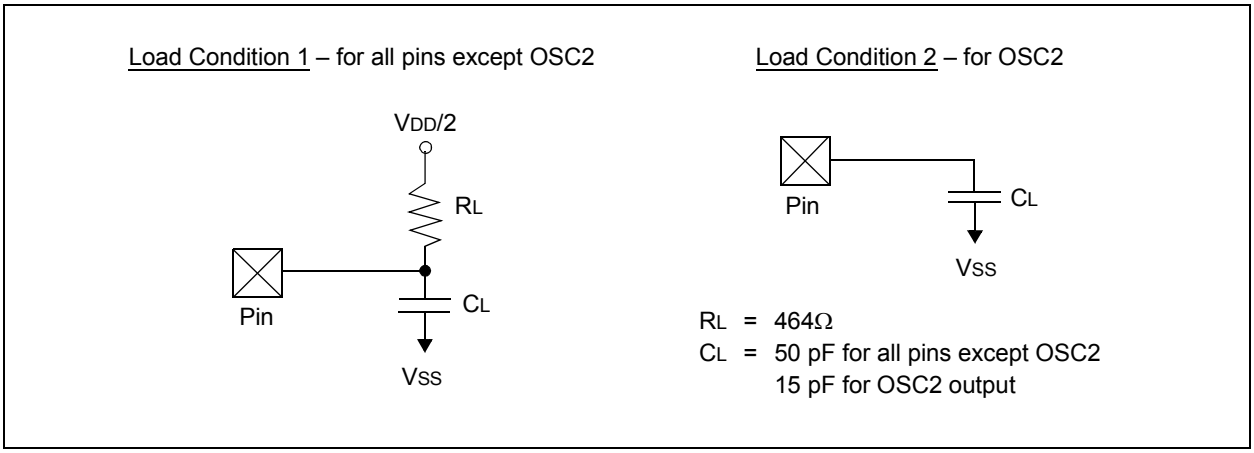


TABLE 25-16: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
DO50	COSCO	OSC2 Pin	—	—	15	pF	In XT and HS modes, when external clock is used to drive OSC1
DO56	CIO	All I/O Pins and OSC2	—	—	50	pF	EC mode
DO58	CB	SCL1, SDA1	—	—	400	pF	In I^2C mode

FIGURE 25-9: HIGH-SPEED PWMx MODULE FAULT TIMING CHARACTERISTICS

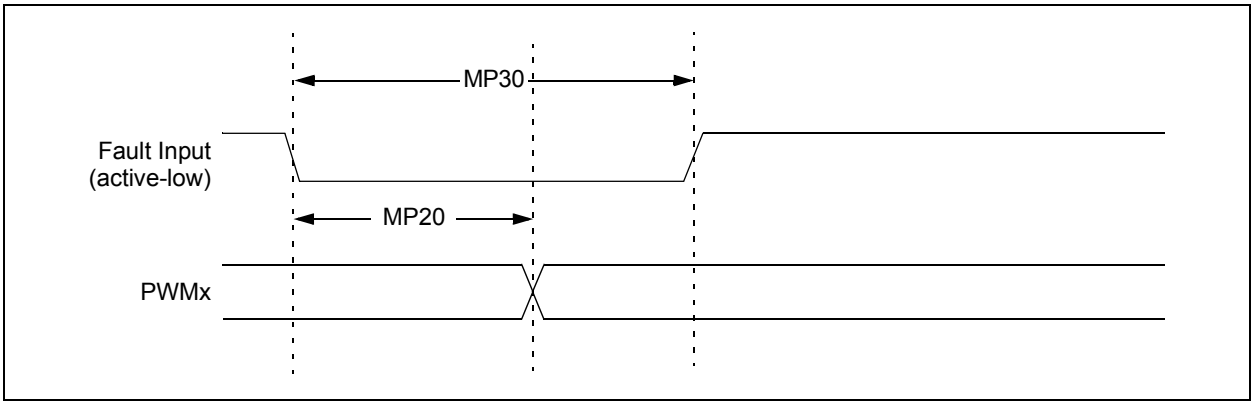
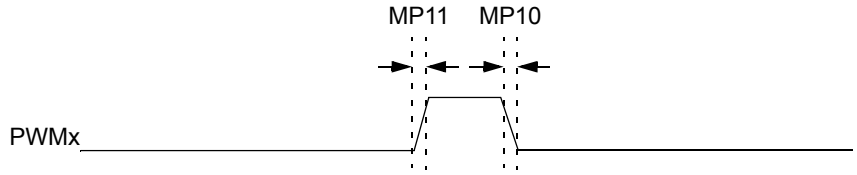


FIGURE 25-10: HIGH-SPEED PWMx MODULE TIMING CHARACTERISTICS



Note: Refer to Figure 25-1 for load conditions.

TABLE 25-30: HIGH-SPEED PWMx MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
MP10	TFPWM	PWMx Output Fall Time	—	—	—	ns	See Parameter DO32
MP11	TRPWM	PWMx Output Rise Time	—	—	—	ns	See Parameter DO31
MP20	TFD	Fault Input ↓ to PWMx I/O Change	—	—	15	ns	
MP30	TFH	Fault Input Pulse Width	15	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

